

## EAST Search History

| Ref # | Hits  | Search Query   | DBs   | Default Operator | Plurals | Time Stamp          |
|-------|-------|--|---|------------------|---------|---------------------|
| L1    | 351   | 425/128.ccls.  | US-PGPUB;<br>USPAT; FPRS;<br>EPO; JPO;<br>DERWENT | OR               | OFF     | 2009/06/08<br>15:13 |
| L2    | 18033 | 257/787.ccls. 257/<br>e21.502.ccls. 257/<br>e21.504.ccls. 257/<br>e21.705.ccls. 257/<br>e23.116.ccls. 257/<br>e23.125.ccls. 438/108.<br>ccls. 438/124.ccls.<br>438/126.ccls.<br>438/127.ccls.<br>156/500.ccls.<br>425/117.ccls.<br>425/125.ccls.<br>425/128.ccls.  | US-PGPUB;<br>USPAT; FPRS;<br>EPO; JPO;<br>DERWENT | OR               | OFF     | 2009/06/08<br>15:14 |
| L3    | 388   | L2 and ((encapsulat<br>\$6 mold\$6 packag\$6<br>resin plastic epoxy)<br>same (semiconductor<br>silicon die dice chip<br>wafer fragment<br>integrated ic<br>component) same<br>(carrier substrate<br>board pwb pcb base)<br>same (cavity feed\$6<br>assembl\$6) same<br>(edge project\$6)<br>same (movable displac<br>\$6 support receiv\$6<br>force part)) | US-PGPUB;<br>USPAT; FPRS;<br>EPO; JPO;<br>DERWENT | OR               | ON      | 2009/06/08<br>15:14 |
| L4    | 424   | ((encapsulat\$6 mold<br>\$6 packag\$6 resin<br>plastic epoxy) same<br>(semiconductor<br>silicon die dice chip<br>wafer fragment<br>integrated ic<br>component) same<br>(carrier substrate<br>board pwb pcb base)<br>same (cavity space<br>open\$6) same (feed<br>\$6 assembl\$6) same<br>(edge project\$6)   | US-PGPUB;<br>USPAT                                | OR               | ON      | 2009/06/08<br>15:31 |

|    |     |  |  |    |    |                     |
|----|-----|--|--|----|----|---------------------|
|    |     | same (mov\$6 displac<br>\$6 adjust\$6) same<br>(support receiv\$6<br>force part)   |  |    |    |                     |
| L5 | 228 | ((encapsulat\$6 mold<br>\$6 packag\$6 resin<br>plastic epoxy) and<br>(semiconductor<br>silicon die dice chip<br>wafer fragment<br>integrated ic<br>component) and<br>(carrier substrate<br>board pwb pcb base)<br>and (cavity space<br>open\$6) and (feed\$6<br>assembl\$6) and<br>(edge project\$6) and<br>(mov\$6 displac\$6<br>adjust\$6) and<br>(support receiv\$6<br>force part)      | FPFRS; EPO;<br>JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2009/06/08<br>15:44 |
| L6 | 547 | ((encapsulat\$6 mold<br>\$6 packag\$6 resin<br>plastic epoxy) and<br>(semiconductor<br>silicon die dice chip<br>wafer fragment<br>integrated ic<br>component) and<br>(carrier substrate<br>board pwb pcb base)<br>and (cavity space<br>open\$6) and (feed\$6<br>assembl\$6) and<br>(edge project\$6) and<br>(mov\$6 displac\$6<br>adjust\$6) and<br>(support receiv\$6<br>force part)).dm. | US-PGPUB                                   | OR | ON | 2009/06/08<br>15:49 |
| L9 | 7   | ((((encapsulat\$6 mold<br>\$6 packag\$6 resin<br>plastic epoxy) near4<br>(semiconductor<br>silicon die dice chip<br>wafer fragment<br>integrated ic<br>component))) and<br>((carrier substrate<br>board pwb pcb base)<br>near6 (cavity space<br>open\$6)) and ((feed<br>\$6 assembl\$6) near6  | US-PGPUB                                   | OR | ON | 2009/06/08<br>15:58 |

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((edge project$6)) and  
((mov$6 displac$6  
adjust$6) near6  
(support receiv$6  
force part))) .csm.
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6/8/09 4:00:18 PM

C:\Documents and Settings\ssmoot\My Documents\EAST\Workspaces\10541715.wsp